

ABSTRACT

An electrochemical mechanical process for electroplating or electropolishing a conductive surface of a wafer is provided. The conductive surface of the wafer is touched by a polishing surface of a compressible pad while a process solution flows through the pad and a potential difference is maintained between the conductive surface and an electrode. The pressure between the polishing surface and a central region of the conductive surface is increased by applying a shaping process to either the conductive surface or the pad.